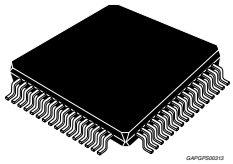
L9369

Automotive IC for a specific application of electric parking braking

Data brief



LQFP64 (10x10x1.4mm)

Features

- AEC-Q100 qualified
- Functional safety concept for ISO26262 compliance
- 4 High-side and Low-side gate pre-drivers for 8 external power NFETs
- Overcurrent protection with programmable thresholds
- Programmable and NFET independent thresholds for VDS monitoring
- 10 integrated Fully differential amplifiers with low offset, very precise gain, and self-test
- 10 separate ADC channels for digital processing of motor current and voltage measurement
- 32-bits - 10 MHz SPI with CRC for internal setting, self-test and diagnostics
- Full drive of external power NFETs down to 5.5 V battery input voltage
- Monitoring on Main power supply and continuous BIST for internal regulators
- Double Bandgap reference
- 4 General Purpose I/O stages (GPIO)
- Button Interface (9 configurable I/O pins) for monitoring and diagnostics in Normal and Sleep Mode.
- 2 Motor Speed Sensors (MSS) interfaces to acquire speed information feedbacks via external Hall sensors.
- System wake-up in Sleep Mode
- Watchdog (configurable via SPI)

Description

The L9369 targets the specific application of electric parking braking, suitable for system configuration in cable-puller or Motor Gear Unit (MGU).

The cores are two H-bridge driver stages to drive 8 external FETs for the rear wheels brakes actuators. The stages are fully driven and configurable via SPI, also in PWM control mode and protected against overcurrent, with drain-source and gate-source voltages monitoring.

A synchronized motor voltages and currents acquisition, is performed via full differential amplifiers with programmable and precise gain and low offset and 10 ADC sigma-delta modulators.

Two configurable HS/LS stages are present with programmable output voltage to drive LED arrays, with feedforward regulation.

2 Motor Speed Sensor interfaces (MSS) are available to acquire position feedback from brake actuators (shared with Lamp driver stage and GPIO).

The set of the interfaces is completed by 4 GPIO (General Purpose I/O) pins and a button interface allows to manage specific customer requirements from Electronic parking braking (EPB) button console both in Normal and Sleep Mode.

Table 1. Device summary

Order code	Package	Packing
L9369-TR	LQFP64	Tape & Reel

For further information contact your local STMicroelectronics sales office. www.st.com

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1 Block diagram and pin description

Figure 1. Simplified block diagram

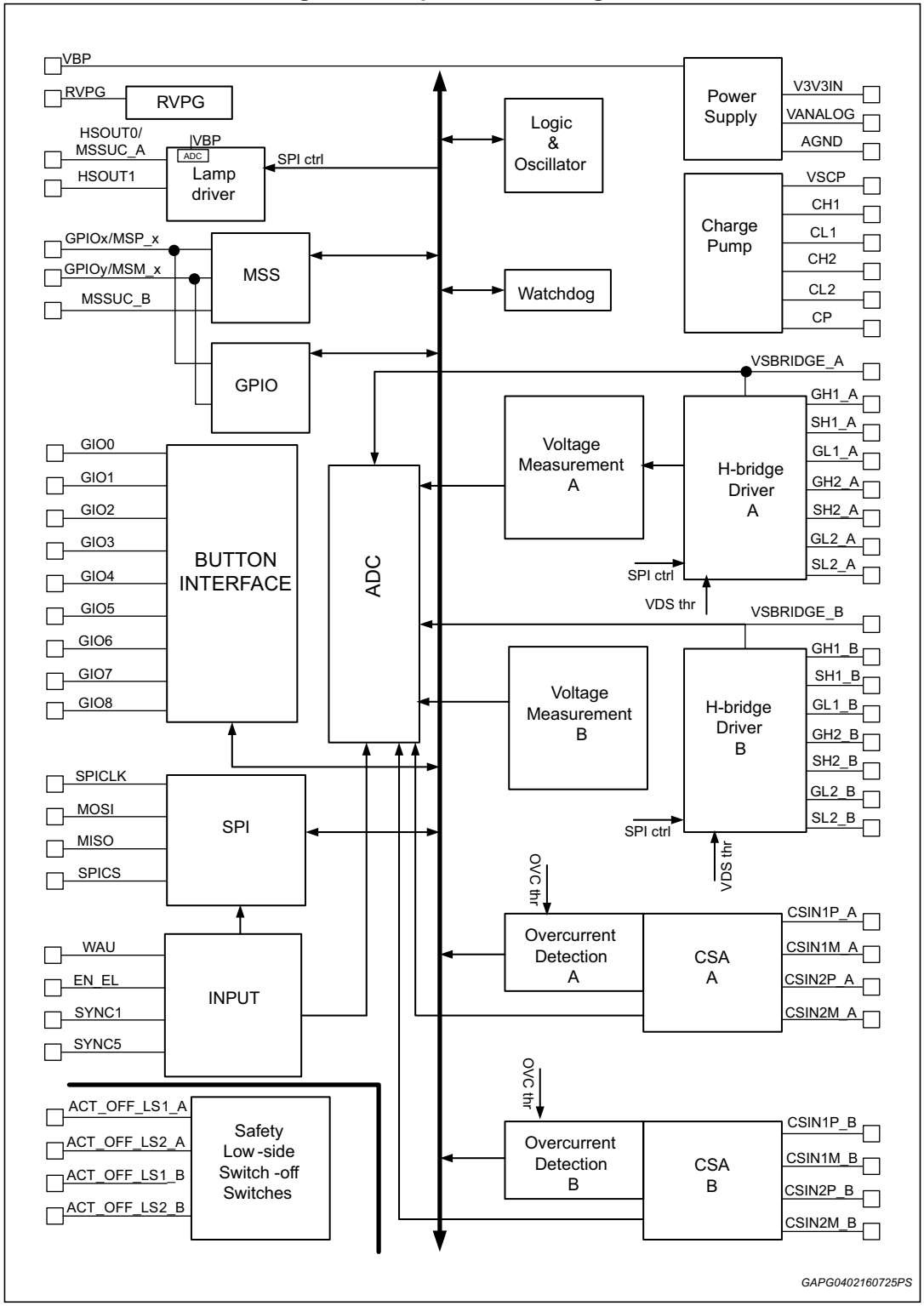
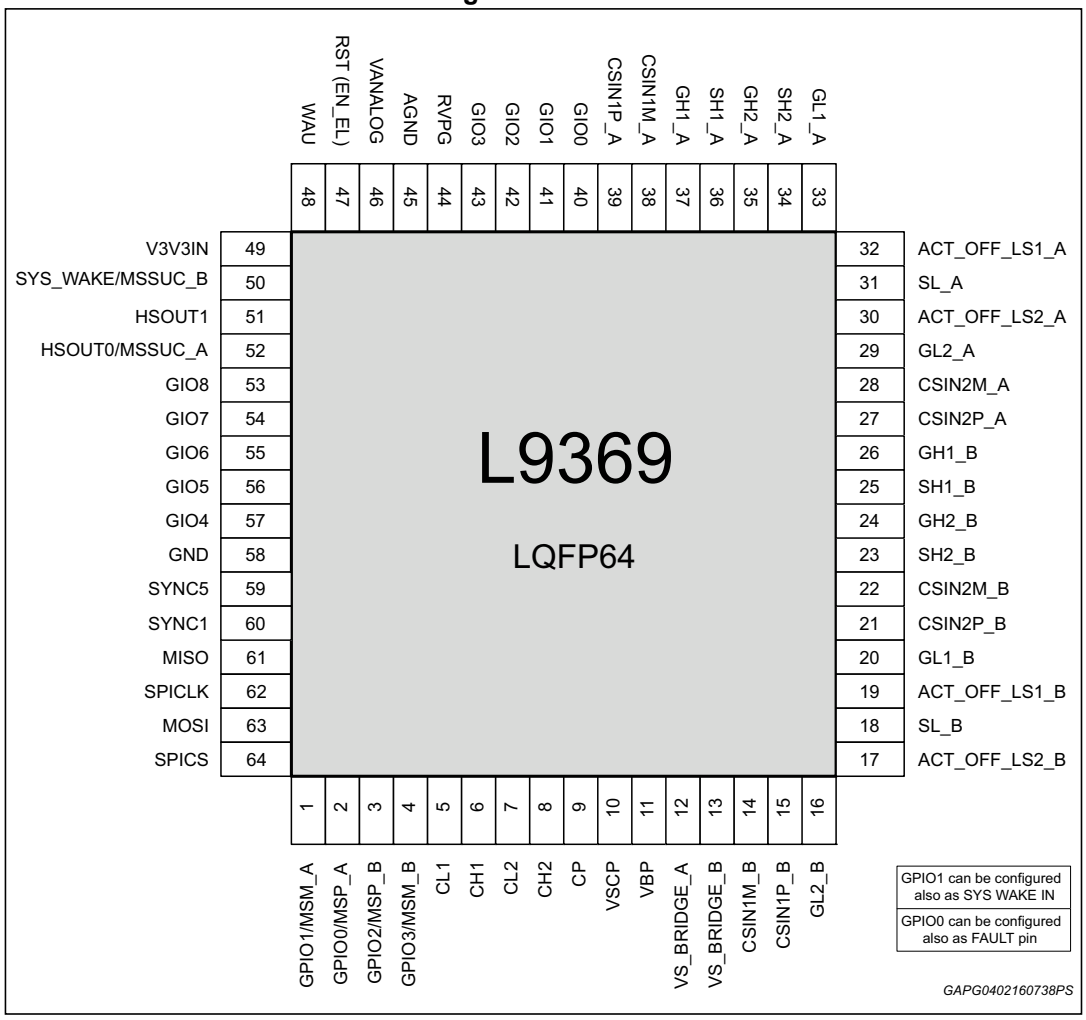


Figure 2. Pin out



PIN-out definition and related functions are described in the following *Table 2*.

Table 2. Pin definition and brief function description

Pin #	Symbol	Function	I/O type
1	SYS_WAKE_IN / (GPIO1) / (MSM_A)	**SYS_WAKE_IN** is a GPIO (General Purpose Programmable input/output) configured by **default** as digital input for system wake-up trigger in Sleep mode only. Configuration is stored in PROM. *(This function needs the **SYS_WAKE** as companion function to work properly, as SYS_WAKE_IN (feedback from ext network) is managed by logic to provide wake-up output pulse to System basis chip (SBC) during sleep mode (WAU=low). MSM_A is disabled due to pin sharing with GPIO block).* ***GPIO1*** = General Purpose Programmable input/output pin. After the 1st start-up **SYS_WAKE_IN** can be disabled via SPI in case not requested by application. ***MSM_A*** = Return pin for the motor speed sensor of stage A with monitoring and short-circuit protection. (**SYS_WAKE_IN** and GPIO1 functionalities are disabled)	I/O
2	GPIO0 / MSP_A (FAULT PIN)	**GPIO0** = General Purpose Programmable input/output pin **MSP_A** = Supply pin for the motor speed sensor of stage A with monitoring short to GND protection and reverse supply protection (*GPIO0 can be configured as Fault pin with programmable fault set via SPI and storage in PROM).*	I/O
3	GPIO2/MSP_B	**GPIO2** = General Purpose Programmable input/output pin **MSP_B** = Supply pin for the motor speed sensor of stage B with monitoring short to GND protection and reverse supply protection	I/O
4	GPIO3/MSM_B	**GPIO3** = General Purpose Programmable input/output pin **MSM_B** = Return pin for the motor speed sensor of stage B with monitoring and short-circuit protection	I/O
5	CL1	Low connection of the stage 1 external pump capacitor	I
6	CH1	High connection of the stage 1external pump capacitor	I
7	CL2	Low connection of the stage 2 external pump capacitor	I
8	CH2	High connection of the stage 2 external pump capacitor	I
9	CP	Charge pump output voltage	O
10	VSCP	Charge pump supply voltage with monitoring	I
11	VBP	Battery supply and redundant supply for charge pump stage.*(Due to PROM data loss, configuration is lost if VBP<VBPpermanent)*	I
12	VSBRIDGE_A	Drain connection of the external H-Bridge High-side NFET and measurement input for H-bridge supply voltage (stage A)	I
13	VSBRIDGE_B	Drain connection of the external H-Bridge High-side NFET and measurement input for H-bridge supply voltage (stage B)	I
14	CSIN1M_B	Negative input pin of the external shunt #1 connected to CSA stage B	I

Table 2. Pin definition and brief function description (continued)

Pin #	Symbol	Function	I/O type
15	CSIN1P_B	Positive input pin of the external shunt #1 connected to CSA stage B	I
16	GL2_B	Gate connection of the H-Bridge Low-side NFET for wheel brake actuator B	O
17	ACT_OFF_LS2_B	Safety LS switch-off switches for H-bridge stage B	I
18	SL_B	Source connection of the H-Bridge Low-side switches for wheel brake actuator B	I
19	ACT_OFF_LS1_B	Safety LS switch-off switches for stage H-bridge B	I
20	GL1_B	Gate connection of the H-Bridge Low-side NFET for right wheel brake actuator B	I
21	CSIN2P_B	Positive input signal of the external shunt #2 connected to redundant CSA for stage B	I
22	CSIN2M_B	Negative input signal of the external shunt #2 connected to redundant CSA for stage B	I
23	SH2_B	Source connection of the H-Bridge High-side NFET for wheel brake actuator B	I
24	GH2_B	Gate connection of the H-Bridge High-side NFET for wheel brake actuator B	O
25	SH1_B	Source connection of the H-Bridge High-side NFET for wheel brake actuator B	I
26	GH1_B	Gate connection of the H-Bridge High-side NFET for wheel brake actuator B	O
27	CSIN2P_A	Positive input signal of the external shunt #2 connected to redundant CSA stage for A	I
28	CSIN2M_A	Negative input signal of the external shunt #2 connected to redundant CSA for stage A	I
29	GL2_A	Gate connection of the H-Bridge Low-side NFET for wheel brake actuator A	O
30	ACT_OFF_LS2_A	Safety LS switch-off switch for stage H-bridge A	I
31	SL_A	Source connection of the H-Bridge Low-side switches for wheel brake actuator A	I
32	ACT_OFF_LS1_A	Safety LS switch-off switch for stage H-bridge A	I
33	GL1_A	Gate connection of the H-Bridge Low-side NFET for wheel brake actuator A	O
34	SH2_A	Source connection of the H-Bridge High-side NFET for wheel brake actuator A	I
35	GH2_A	Gate connection of the H-Bridge High-side NFET for wheel brake actuator A	O
36	SH1_A	Source connection of the H-Bridge High-side NFET for wheel brake actuator A	I

Table 2. Pin definition and brief function description (continued)

Pin #	Symbol	Function	I/O type
37	GH1_A	Gate connection of the H-Bridge High-side NFET for wheel brake actuator A	O
38	CSIN1M_A	Negative input signal of the external shunt #1 connected to CSA for stage A	I
39	CSIN1P_A	Positive input signal of the external shunt #1 connected to CSA for stage A	I
40	GIO0	Programmable Input / Output for Button Interface control	I/O
41	GIO1	Programmable Input / Output for Button Interface control	I/O
42	GIO2	Programmable Input / Output for Button Interface control	I/O
43	GIO3	Programmable Input / Output for Button Interface control	I/O
44	RVPG	Gate driver output for reverse voltage switch control	O
45	AGND	Analog reference ground connection	GND
46	VANALOG	L9369 generated Low noise analog voltage, supplies the internal current measurement path. *(It can be used to supply external circuits with low current consumption. External capacitor required for stabilization.)*	O
47	RST (EN_EL)	***EN_EL***: digital enable input for GPIO (default pin function). ***RST***: High active Input Reset pin. *(Enabled via dedicated SPI bit. GPIO block can be enabled and configured independently)*	I
48	WAU	Wake-up input. (*digital input*, *low level active to enter Sleep Mode*)	I
49	V3V3VIN	3.3 V supply voltage for L9369 output buffers	I
50	SYS_WAKE/MSSUC_B	***SYS WAKE*** (default configuration at start-up) is a digital output pin to wake System basis chip (SBC) up as support for general diagnostics on the external button during Sleep Mode only. This function/pin needs the ***SYS_WAKE_IN*** as companion function to work properly. MSSUC_B is disabled due to pin sharing with GPIO block. In case the ***SYS_WAKE*** function is not requested by application, It can be disabled via SPI at 1st start-up and the pin can be configured as: ***MSSUC_B*** = Motor speed sensor signal output to the µC. *(MSS interface is disabled by default and its functionality is shared with Lamp driver HSOUT).*	O
51	HSOUT1	HSOUT1 = SPI programmable HS/LS current source for external bulb lamp or LED array with monitoring	O
52	HSOUT0/MSSUC_A	**HSOUT0** = SPI programmable HS/LS current source for external bulb lamp or LED array with monitoring **MSSUC_A** = Motor speed sensor signal output to the µC. *MSS interface is disabled by default.*	O
53	GIO8	Programmable Input / Output for Button Interface control	I/O

Table 2. Pin definition and brief function description (continued)

Pin #	Symbol	Function	I/O type
54	GIO7	Programmable Input / Output for Button Interface control	I/O
55	GIO6	Programmable Input / Output for Button Interface control	I/O
56	GIO5	Programmable Input / Output for Button Interface control	I/O
57	GIO4	Programmable Input / Output for Button Interface control	I/O
58	GND	Digital and power ground connection	GND
59	SYNC5	Synchronization signal from µC for ADC voltage/current measurement path	I
60	SYNC1	Synchronization signal from µC for ADC voltage/current measurement path	I
61	MISO	Serial data out for SPI communication to µC	O
62	SPICLK	Clock signal for SPI	I
63	MOSI	Serial data input for SPI communication from µC	I
64	SPICS	Chip select for SPI	I

Table 3. General conditions

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit	Parameter ID
$T_{junction}$	Function temperature	(parameters guaranteed)	-40	-	175	°C	L9369_194
R_{th}	Application specific R_{th}	(Housing mounted on 6-Layer PCB)	-	-	40	°C/W	L9369_3052

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

2.1 LQFP64 (10x10x1.4 mm) package information

Figure 3. LQFP64 (10x10x1.4 mm) package outline

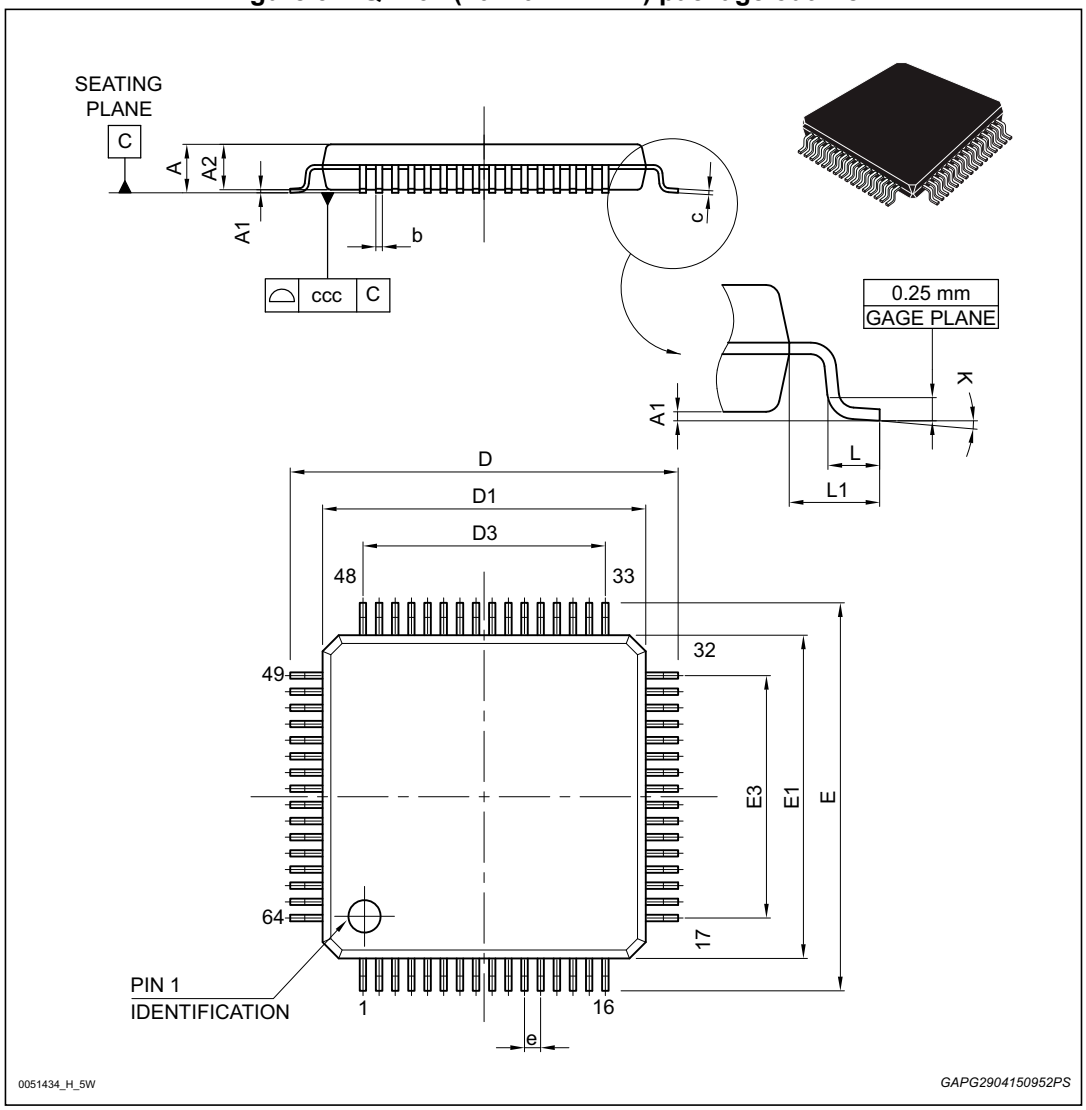


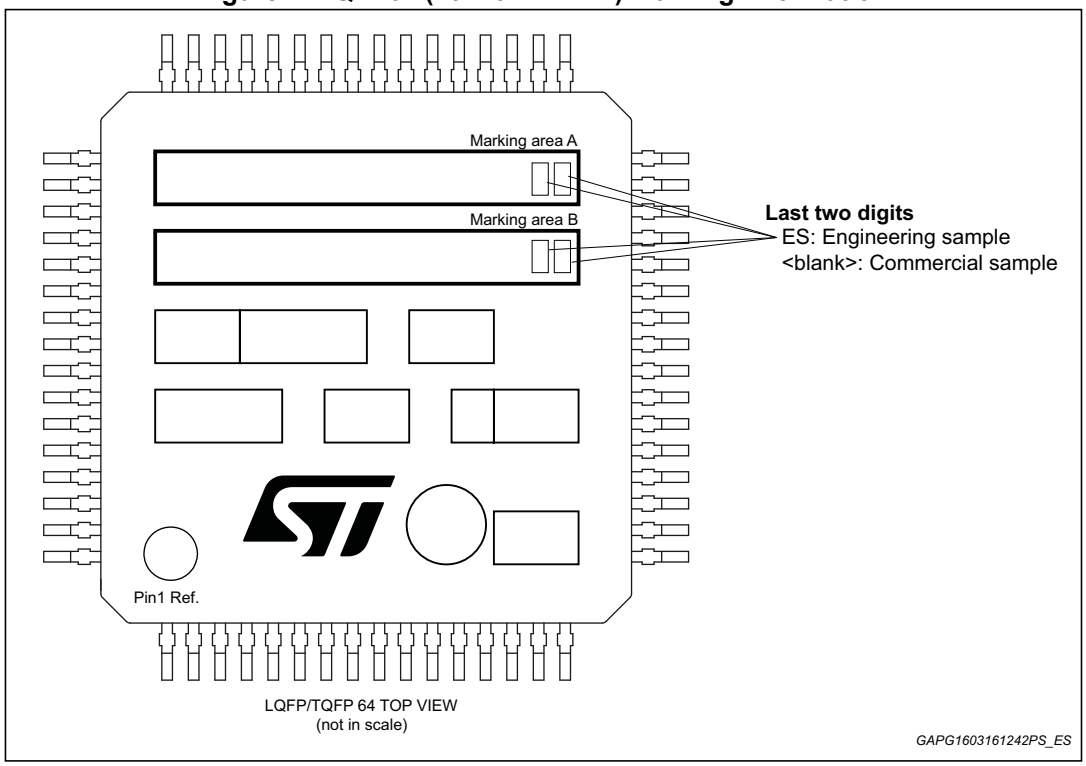
Table 4. LQFP64 (10x10x1.4 mm) package mechanical data

Ref	Dimensions					
	Millimeters			Inches[1]		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	-	1.60	-	-	0.0630
A1	0.05	-	0.15	0.0020	-	0.0059
A2	1.350	1.40	1.45	0.0531	0.0551	0.0571
b	0.17	0.22	0.27	0.0067	0.0087	0.0106
c	0.09	-	0.20	0.0035	-	0.0079
D	11.80	12.00	12.20	0.4646	0.4724	0.4803
D1	9.80	10.00	10.20	0.3858	0.3937	0.4016
D3	-	7.50	-	-	0.2953	-
E	11.80	12.00	12.20	0.4646	0.4724	0.4803
E1	9.80	10.00	10.20	0.3858	0.3937	0.4016
E3	-	7.50	-	-	0.2953	-
e	-	0.50	-	-	0.0197	-
L	0.45	0.60	0.75	0.0177	0.0236	0.0295
L1	-	1.00	-	-	0.0394	-
K	0° (min.), 3.5° (typ.) 7° (max.)					
ccc	-	-	0.08	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

2.2 LQFP64 (10x10x1.4 mm) marking information

Figure 4. LQFP64 (10x10x1.4 mm) marking information



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3 Revision history

Table 5. Document revision history

Date	Revision	Changes
11-Jan-2019	1	Initial release.

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